

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free):   XC6804xxxxQR-G  
Typical Mass:           80     mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	1.678	Silicon	21000	7440-21-3
	-	Arsenic	<1	7440-38-2
Leadframe	26.731	Copper	334100	7440-50-8
	0.358	Iron	4500	7439-89-6
	0.019	Zinc	200	7440-66-6
	0.013	Phosphorus	200	7723-14-0
	0.219	Silver	2700	7440-22-4
Die attach	0.414	Silver	5200	7440-22-4
	0.054	Epoxy resin	700	—
	0.004	Phenol resin	100	—
Bonding wire	0.060	Gold	800	7440-57-5
Resin	43.755	Silica	546900	60676-86-0
	3.923	Epoxy resin	49000	—
	0.853	Phenol resin	10700	—
	0.597	Silica (crystal)	7500	14808-60-7
Plating	1.321	Tin	16500	7440-31-5

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."